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(54) PLATING METHOD OF METAL DISPERSED WITH PARTICLES

(57)Abstract:

PURPOSE: To form a noble metal plating layer having various excellent characteristics at a low cost in the stage of forming a plating layer of noble metals or an alloy contg. noble metals by dispersing and codepositing specific inorg. particles and metallic particles in the plating layer.

CONSTITUTION: A plating layer of noble metals such as Pd, Au, In, Ru or the like or a plating layer of their alloy is formed on the electrical contact part of a relay, switch, contact point, etc. in order to improve the resistance to corrosion and wear, high conductivity and the resistance to wear by arc. Hard inorg. particles or lubricative inorg. particles of carbide, oxide, boride, nitride, etc. are suspended in a concn. of 5W500g/l with grain sizes as fine as 0.01W10 μ in the plating bath of the above-mentioned noble metal or noble metal alloy and further particles of about the same degree as the metal composing the plating bath are suspended in an amt. of 1/20W1/2 of the amt. of the inorg. particles, then plating is performed. The noble metal plating layer dispersed and codeposited uniformly with the inorg. particles and metallic particles is obtd. at a low cost.

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